



100% Material Declaration Data Sheet BGG256

PK214 (v1.0) January 15, 2007

Material Declaration Data Sheet

Average Weight: 2.7915 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0597	2.14%
	Silicon	7440-21-3	100.00		0.0597	
Die Attach Material					0.0062	0.22%
	Resin	Trade Secret	22.00		0.0014	
	Silver	7440-22-4	78.00		0.0048	
Mold Compound					1.0962	39.27%
	Resin	Trade Secret	12.00		0.1315	
	Silica	60676-86-0	88.00	Filler	0.9647	
Laminate					1.1401	40.84%
	Bismaleimide / Triazine	13676-54-6 / 225722-66-1	9.36		0.1067	
	Glass fiber	65997-17-3	39.89		0.4547	
	Epoxy resin	68541-56-0 / 29690-82-2 / 25068-38-6	7.70		0.0878	
	Copper	7440-50-8	40.90	Metal Layer	0.4662	
	Nickel	7440-02-0	1.80	Metal Layer	0.0206	
	Gold	7440-57-5	0.36	Metal Layer	0.0041	
Wire					0.0212	0.76%
	Gold	7440-57-5	100.00		0.0212	
Solder Balls					0.4681	16.77%
	Tin	7440-31-5	95.50		0.4470	
	Silver	7440-22-4	4.0		0.0187	
	Copper	7440-50-8	0.5		0.0023	

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1

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
1/15/07	1.0	Initial release.